

SOT740-3

LPGA256; plastic, low profile ball grid array; 256 bumps; 1.0 mm pitch; 17 mm x 17 mm x 1.7 mm body

21 January 2019

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	LPGA256
Package type industry code	LPGA256
Package style descriptive code	LPGA (low profile ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	07-01-2016
Manufacturer package code	98ASA00346D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	17	-	mm
package width	-	17	-	mm
seated height	-	1.7	-	mm
nominal pitch	-	1	-	mm
actual quantity of termination	-	256	-	



LPGA256; plastic, low profile ball grid array; 256 bumps; 1.0 mm pitch; 17 mm x 17 mm x 1.7 mm body

2 Package outline

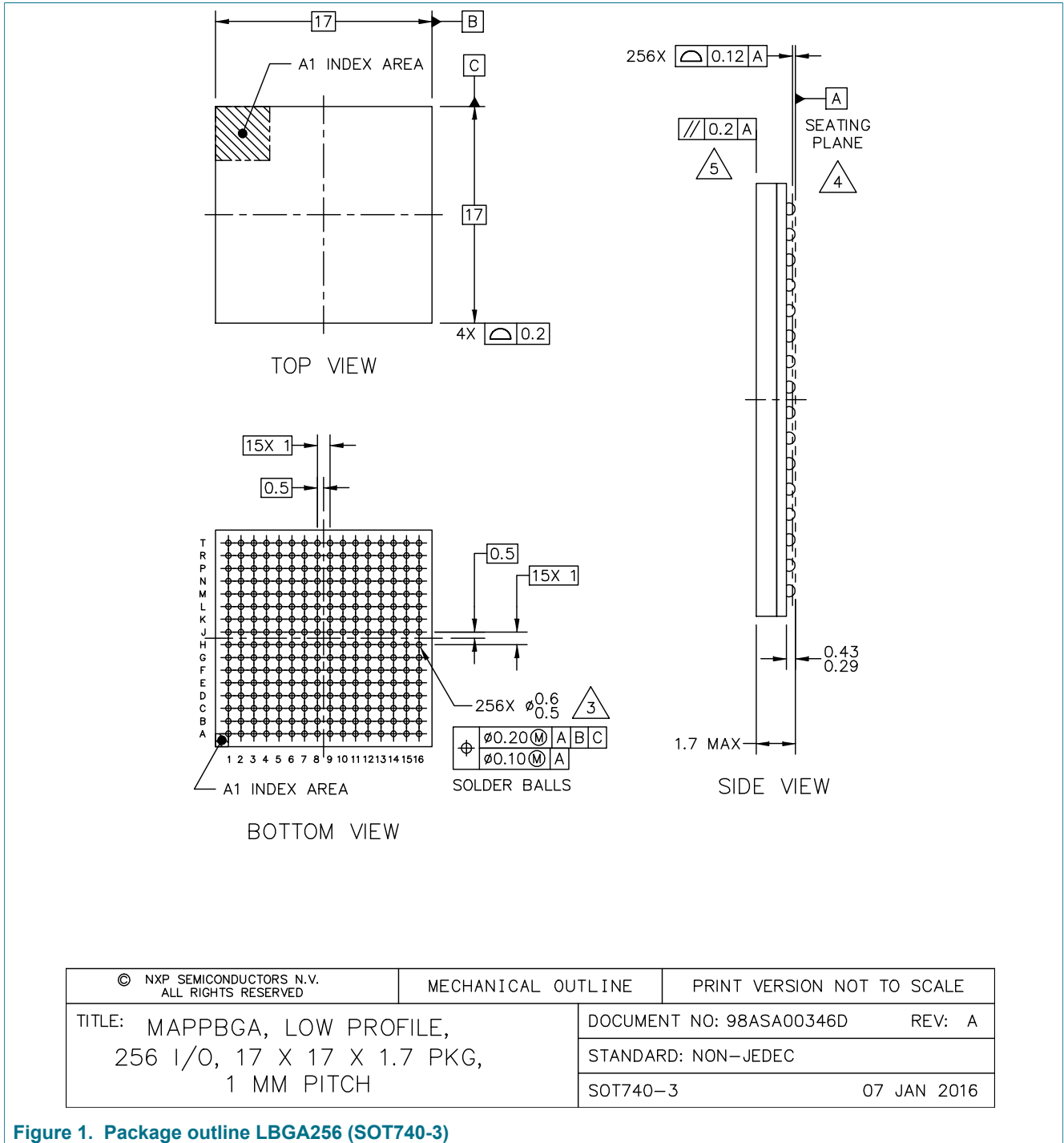


Figure 1. Package outline LPGA256 (SOT740-3)

LPGA256; plastic, low profile ball grid array; 256 bumps; 1.0 mm pitch; 17 mm x 17 mm x 1.7 mm body

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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TITLE: MAPPBGA, LOW PROFILE, 256 I/O, 17 X 17 X 1.7 PKG, 1 MM PITCH	DOCUMENT NO: 98ASA00346D	REV: A
	STANDARD: NON-JEDEC	
	SOT740-3	07 JAN 2016

Figure 2. Package outline note LPGA256 (SOT740-3)

3 Legal information

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